

**Minutes of the CE-2.0 National Connectors Standards Committee
October 4-5, 2004
San Diego, CA**

Members Present

David Bouzek (Tri-Star Electronics)
Bill Peverill (WPA)
Frank Ruffino (Molex)
Bill Upstone (Cannon)
Greg Brown (Glenair)

Liaison Members Present

None

Others Present

Carl Fritz (Guest)

Members Absent

Jeff Toran (FCI)
Al Davis (Amphenol)
Max Peel (Contech Research)
H. John Healey (IBM)
Harvey Waltersdorf
Rick Zulkiewicz (Raytheon)
Bob Druckenmiller (FCI)
Arun Shah (Cinch)

Meeting number 35 of the National Connectors Standards Committee convened at 10:00 AM on October 4, 2004 by Vice Chairman, Bill Upstone.

1. REVIEW AND APPROVAL OF MINUTES

The minutes of Meeting No. 34 held in Tampa, FL were approved as published.

2. CHAIRMAN'S REPORT

A. Ed Mikoski (ECA) reported that Chairman Harvey Waltersdorf was unable to attend the meeting due to the fact that he was no longer employed by AVX Corporation. It is unlikely that he will continue as chairman.

B. John Healey (IBM), Ralph Antonelli (DSCC) and Jeff Toran (FCI) were not able to attend due to business commitments.

C. Ed Mikoski indicated that environmental and lead free issues are hot topics that are being discussed within the Soldering Technology Committee.

D. Bill Peverill indicated that Ralph Antonelli (614) 692-0576, e-mail ralph.antonelli@dla.mil, would be representing DSCC in the future.

E. Frank Ruffino indicated that he would prepare an abstract on the development of a test specification for current rating power connectors. Ed Mikoski indicated that such a project could spur interest in attendance at future meetings.

3. SUBCOMMITTEE MEETINGS

CE-2.1 Test Procedures-Chairman: Bill Peverill, Vice Chairman: Max Peel
The Test Procedures Subcommittee was convened by Bill Peverill (see Attachment No. 1 for meeting report).

CE-2.2 Circular Connector Specifications-Chairman: Al Davis
No report.

CE-2.3 Rectangular Connector Specifications-Chairman: TBD
No report.

CE-2.4 Printed Board Connector Specifications-Chairman: TBD
No report.

CE-2.5 Backplane Specifications-Chairman: TBD
It was moved by Bill Peverill and seconded by David Bouzek to cancel the subcommittee. It was unanimously approved by those present.

CE-2.6 Contact Specifications-Chairman: Dave Bouzek
David Bouzek reported that round robin testing on high strength nickel wire has been performed by Amphenol and Deutsch, Tri-Star is in process and Cannon will follow.

CE-2.7 Editing Subcommittee-Chairman: Carl Fritz
Nothing special to report.

CE-2.8 International Standards Subcommittee: Chairman: Jeff Toran
Jeff Toran submitted a report and indicated that the next meeting of IEC 48B is slated for 12-14 October 2004 in Beijing China.

CE-2.9 Sockets Subcommittee-Chairman: TBD
The socket subcommittee was convened by Bill Upstone (see Attachment No. 2 for meeting report).

4. WORKING GROUP MEETINGS

CE-2.0.1 Contact and Connector Plating-Chairman: Bill Upstone
No activity.

CE-2.0.4 Connector Outlines & Surface Mount Activities
No report.

5. SPECIAL TASK GROUP MEETINGS

STG-13-2.0 Terminology-Chairman: TBD
No report.

STG-20-2.0 Space Requirements-Chairman: TBD
Bill Upstone indicated that he would contact Ron Hodge at (256) 544-3420 concerning future meeting attendance in place of Charles Gamble from NASA.

STG-23-2.0 Current vs Temperature Rise-Chairman: Max Peel
It was moved by Bill Peverill and seconded by David Bouzek to cancel this STG since it is now covered in CE-2.1 by EIA-364-1000.02, PN-3787. It was unanimously approved by those in attendance.

6. LIASION REPORTS

A. DSCC (Including Army, Air Force, & Navy (except NAVAIR)
No report.

B. NAVAIR LAKEHURST REPORT
No report.

C. SAE
No report.

D. ASTM
No report.

E. NASA
No report

F. IICIT
The 37th IICIT Symposium was held in Detroit 13-15 September 2004. A paper on the subject of Current Rating Power Connectors Using Voltage Drop Criteria by Frank Ruffino and Bob Malucci received the best of conference award.

7. OLD BUSINESS

Tin Wiskers Test Procedures (Max Peel)
No report. Frank Ruffino reported that there is already a agenda item for developing a test procedure for evaluating the potential for tin whiskers and a test procedure for evaluating resistance to soldering heat in lead free products. No new project is required.

8. NEW BUSINESS

No New business

9. FUTURE MEETINGS

Date for the next meeting will be 16-17 May 2005, in New Orleans, LA.

The meeting adjourned at 5:30 PM on 4 October 2004.

This meeting was conducted in accordance with EIA Legal Guidelines and EIA Manual for Organization and Procedure.

Carl E. Fritz, Recording Secretary

Wm. Peverill, Secretary
EIA/ECA CE-2.0

Bill Upstone, Acting Chairman
EIA/ECA CE-2.0